

Patent

Customer No.: 31561  
Docket No.10039-US-PA  
Application No.: 10/605,215**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Chen et al  
Application No. : 10/605,215  
Filed : 2003/9/16  
For : FLIP-CHIP SUBSTRATE AND FLIP-CHIP BONDING  
PROCESS THEREOF  
Art Unit : 2811  
Examiner : IM, JUNGHWAM

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**TRANSMITTAL LETTER**

002-1-703-872-9306

(Via fax: 1+5 pages)

**RECEIVED  
CENTRAL FAX CENTER****DEC 28 2004**Assistant Commissioner for Patents  
Arlington, Virginia 22202

Dear Sir,

In response to the Office Action dated December 14, 2004(paper No. 20041207), please find the *Response to Restriction Requirement* in 5 pages.

I believe that no fee is incurred. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10039-US-PA)

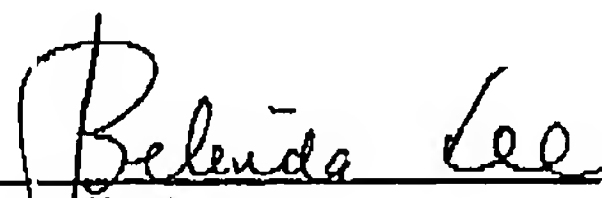
Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date:

Dec 28, 2004

By:

  
Belinda Lee  
Registration No.: 46,863

Please send future correspondence to:

7F, -1, No. 100, Roosevelt Rd.,

Sec. 2, Taipei 100, Taiwan, R.O.C.

Tel: 886-2-2369 2800 Fax: 886-2-2369 7233 / 886-2-2369 7234

E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw

